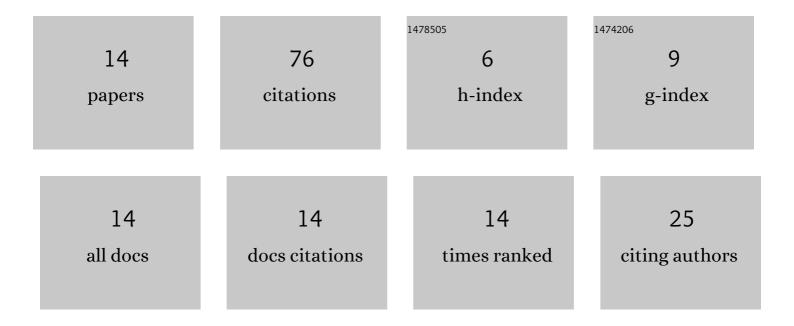
Chun-Hao Chen

List of Publications by Year in descending order

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CHUN-HAO CHEN

| # | Article | IF | CITATIONS |
|----|--|-----|-----------|
| 1 | Intermetallic Growth at the Interfaces Between Zn4Sb3 Thermoelectric Material and Various Metallic Electrodes. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2022, 53, 136. | 2.2 | 0 |
| 2 | Microstructure evolution and failure mechanism of electromigration in Ag-alloy bonding wire. Journal of Alloys and Compounds, 2022, 913, 165266. | 5.5 | 7 |
| 3 | Interfacial Reactions of Ag and Ag-4Pd Stud Bumps with Sn-3Ag-0.5Cu Solder for Flip Chip Packaging. Journal of Electronic Materials, 2021, 50, 249-257. | 2.2 | 1 |
| 4 | Grain growth and twin formation in a Ag-4Pd alloy ribbon after annealing treatments. Journal of Alloys and Compounds, 2021, 863, 158619. | 5.5 | 8 |
| 5 | Effects of Grain Size on the Ag Dissolution and Ion Migration of Ag-4Pd Alloy Wires. Journal of Electronic Materials, 2021, 50, 5955-5964. | 2.2 | 3 |
| 6 | Interfacial reactions in Zn4Sb3/titanium diffusion couples. Journal of Alloys and Compounds, 2021, 881, 160630. | 5.5 | 1 |
| 7 | Effect of Post-Weld Heat Treatment on the Solid-State Diffusion Bonding of 6061 Aluminum Alloy. Applied Sciences (Switzerland), 2021, 11, 9660. | 2.5 | 9 |
| 8 | Ultrasonic Bonding of Ag and Ag-Alloy Ribbon—An Innovative Alternative for High Power IC Packages. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1061-1068. | 2.5 | 7 |
| 9 | Improvement of Sn-3Ag-0.5Cu Soldered Joints Between Bi0.5Sb1.5Te3 Thermoelectric Material and a Cu Electrode. Journal of Electronic Materials, 2020, 49, 3391-3399. | 2.2 | 7 |
| 10 | Intermetallic Compounds at the Interfaces of Ag–Pd Alloy Stud Bumps With Al Pads. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1657-1665. | 2.5 | 7 |
| 11 | Evaluation of Corrosion Resistance of Ag-Alloy Bonding Wires for Electronic Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 146-153. | 2.5 | 12 |
| 12 | Electrolytic Migration of Ag-Pd Alloy Wires with Various Pd Contents. Journal of Electronic Materials, 2018, 47, 3634-3638. | 2.2 | 5 |
| 13 | Mechanism of the Electromigration in Ag-Pd Alloy Bonding Wires. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2018, 49, 5904-5910. | 2.2 | 9 |
| | | | |

14 Applications of Ag-alloy stud bump for IC and LED packages. , 2014, , .

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